

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BGSA 20VGL8 E6327	**Issued**	4. July 2019
MA#	MA004645450		
Package	PG-TSLP-8-1	**Weight***	1.07 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.381	35.45	35.45	354483	354483
bumps	non noble metal	copper	7440-50-8	0.009	0.84	0.84	8450	8450
leadframe	non noble metal	nickel	7440-02-0	0.094	8.76	8.76	87570	87570
encapsulation	organic material	carbon black	1333-86-4	0.003	0.26		2573	
	plastics	epoxy resin	-	0.080	7.46		74615	
	inorganic material	silicondioxide	60676-86-0	0.470	43.74	51.46	437399	514587
leadfinish	noble metal	gold	7440-57-5	0.012	1.15	1.15	11490	11490
plating	noble metal	silver	7440-22-4	0.020	1.88	1.88	18763	18763
solder	noble metal	silver	7440-22-4	0.000	0.01		83	
	non noble metal	tin	7440-31-5	0.005	0.45	0.46	4515	4598
ubm	non noble metal	tungsten	7440-33-7	0.000	0.00		7	
	non noble metal	titanium	7440-32-6	0.000	0.00		14	
	non noble metal	copper	7440-50-8	0.000	0.00	0.00	38	59
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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